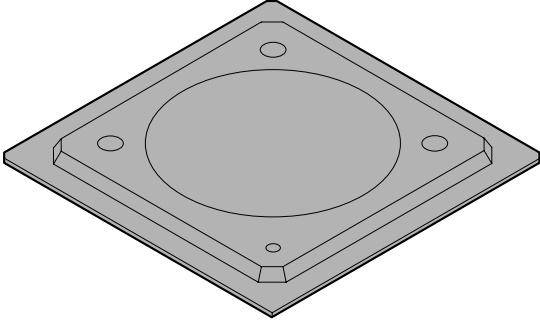
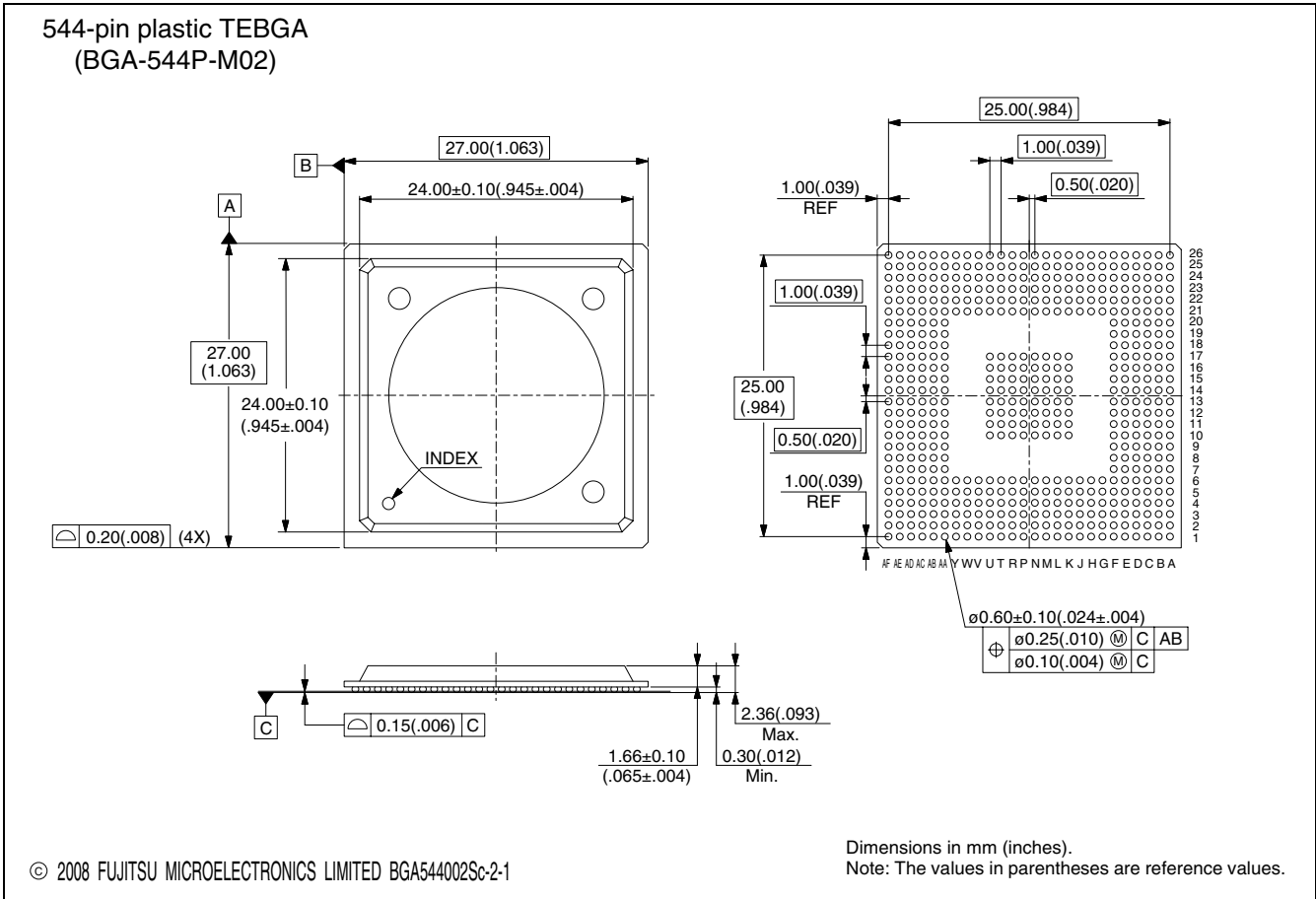


BGA-544P-M02

<p>544-pin plastic TEBGA</p>  <p>(BGA-544P-M02)</p>	Lead pitch	1.00 mm
	Package width × package length	27.00 mm × 27.00 mm
	Lead shape	Ball
	Sealing method	Plastic mold
	Mounting height	2.36 mm MAX
	Weight	3.70 g



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Customers are advised to consult with FUJITSU MICROELECTRONICS sales representatives before ordering.
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